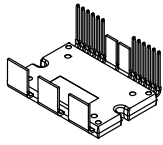
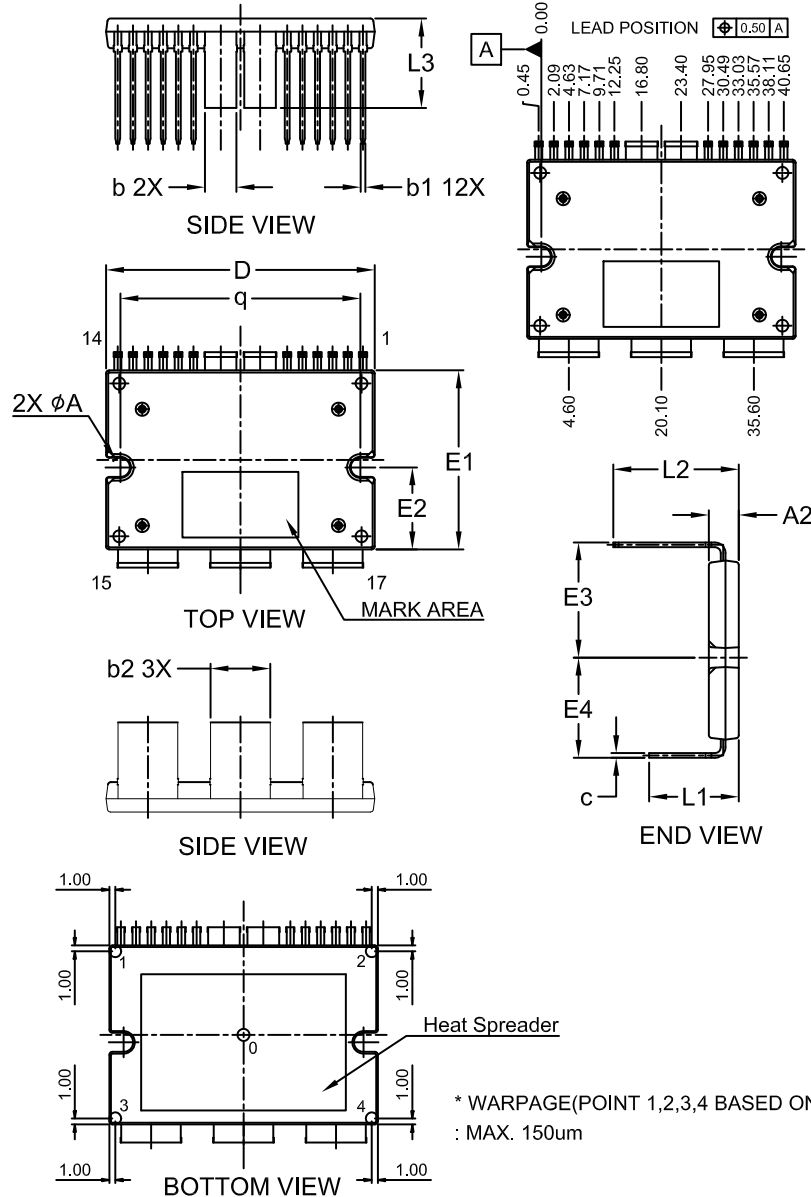


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



APM17-MDC CASE MODHH ISSUE C

DATE 08 DEC 2021

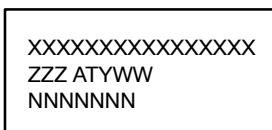


NOTES:

1. DIMENSIONING AND TOLERANCING PER. ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A2	4.90	5.00	5.10
b	5.20	5.30	5.40
b1	0.70	0.80	0.90
b2	9.90	10.00	10.10
c	0.75	0.80	0.90
D	44.90	45.00	45.10
E1	29.90	30.00	30.10
E2	13.65	13.75	13.85
E3	19.00	19.30	19.60
E4	16.50	16.80	17.10
L1	14.70	15.00	15.30
L2	20.70	21.00	21.30
L3	14.70	15.00	15.30
q	40.10	40.20	40.30
ϕA	3.10	3.20	3.30

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
 ZZZ = Lot ID
 AT = Assembly & Test Location
 Y = Year
 W = Work Week
 NNN = Serial Number

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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